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(12) **United States Design Patent**
Yamauchi

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(54) **SEMICONDUCTOR MODULE**

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USPC

(58) **Field of Classification Search**

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361/679.01, 713, 728, 736, 760, 761, 772,
361/775, 783, 820; 174/250, 523;
438/15, 25, 26, 51, 55, 63, 64, 106
CPC . H01L 21/00; H01L 2224/42; H01L 2224/43;
H01L 21/4814; H01L 21/4846; H01L
21/4871; H01L 21/67144; H01L 23/12;
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2924/1715; H01L 2924/17151; H01L
2924/181; H01L 2924/1811; H01L
2924/1815; H01L 2924/19042; H01L
2924/1905; H01L 2224/08054; H01L
23/58; H01L 2021/02; H01L 2021/04;
H05B 41/14; H02B 6/4201; G02B
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G02B 6/4262; G02B 6/428; G02B
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See application file for complete search history.

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(57)

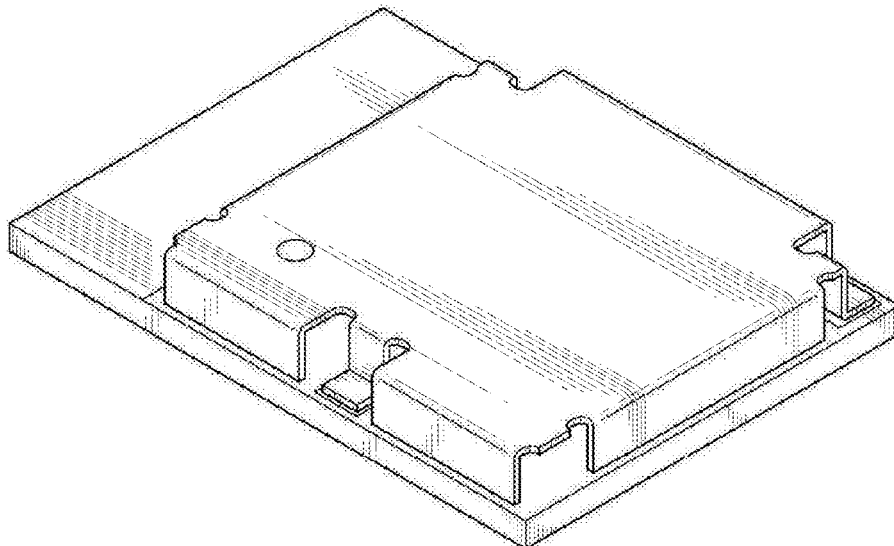
CLAIM

The ornamental design for a semiconductor module, as shown and described.

DESCRIPTION

FIG. 1 is a perspective view of semiconductor module showing my new design;
FIG. 2 is a top view thereof;
FIG. 3 is a bottom view thereof;
FIG. 4 is a front view thereof;
FIG. 5 is a rear view thereof;
FIG. 6 is a right-side view thereof; and,
FIG. 7 is a left-side view thereof.

1 Claim, 7 Drawing Sheets



(56)

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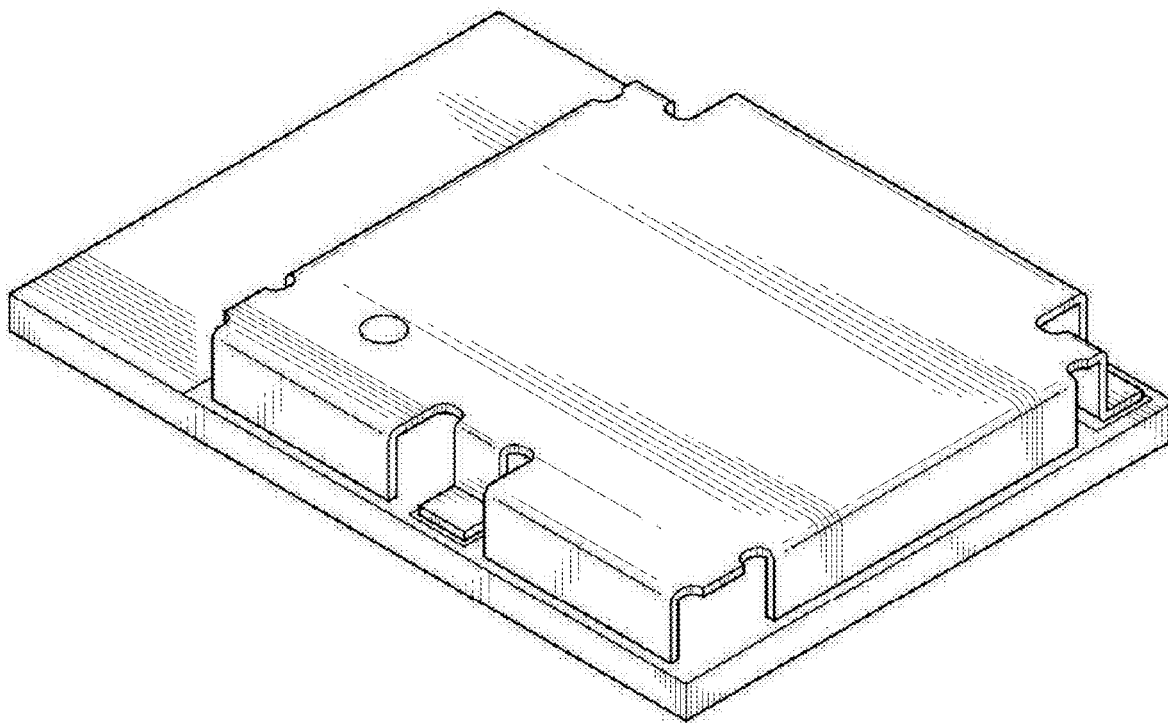


FIG. 1

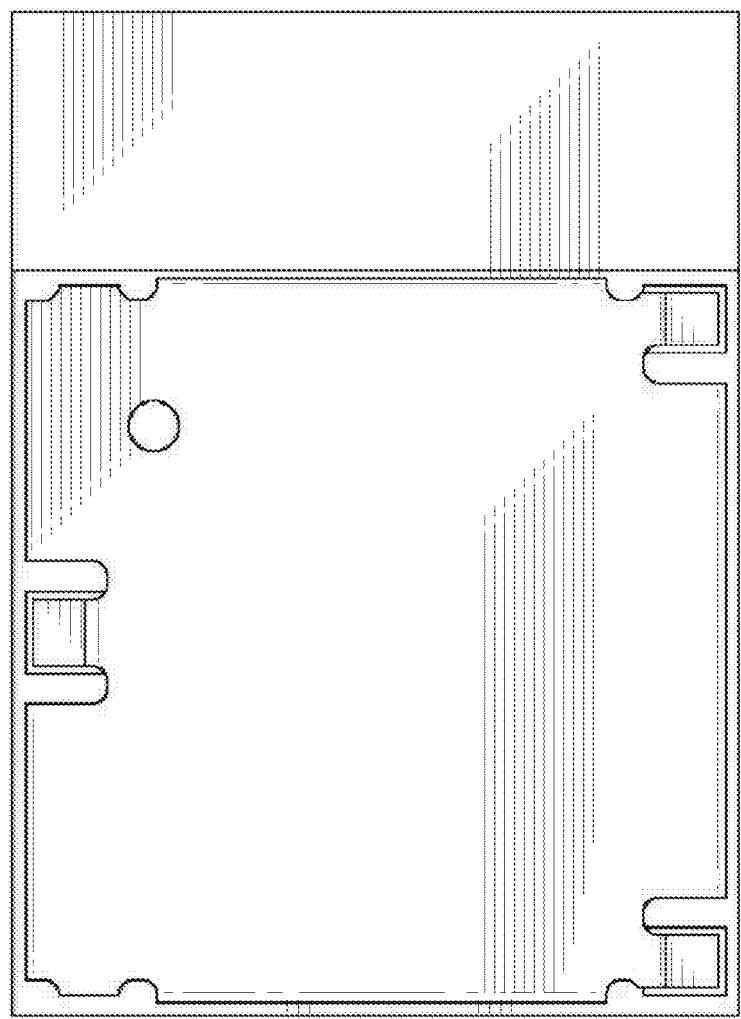


FIG. 2

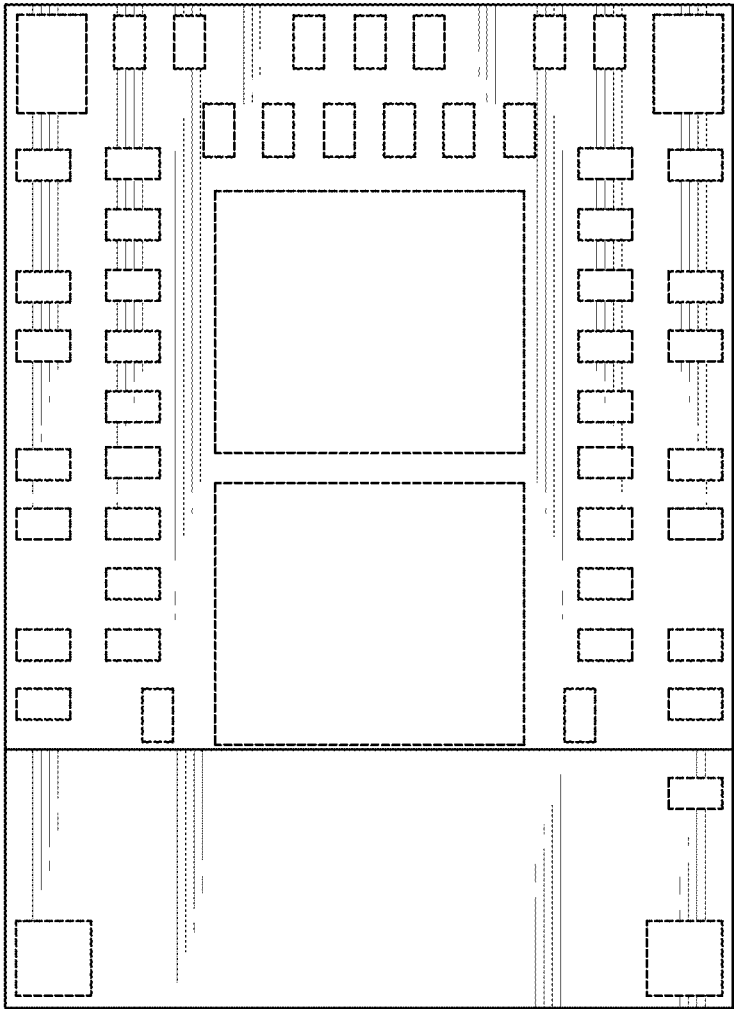


FIG. 3



FIG. 4

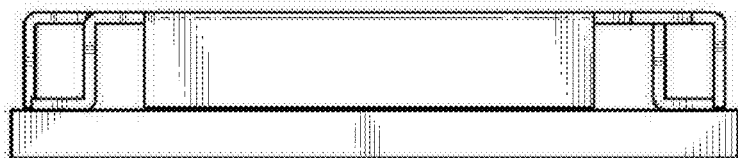


FIG. 5

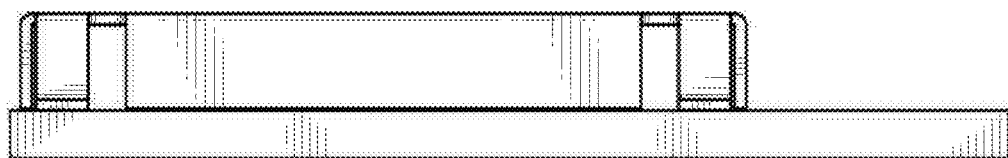


FIG. 6

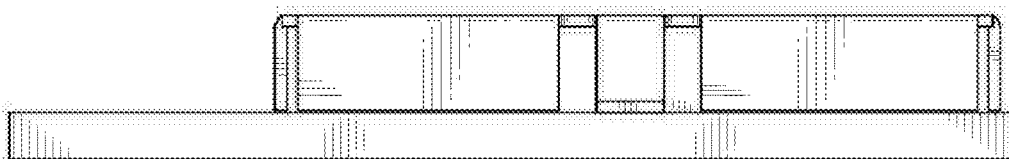


FIG. 7